L Numb r	Hits	Search T xt	DB	Time stamp
500	5115	(sta k or stacking or stacked) and	USPAT;	2004/06/17
		((sub trat rint rp ser rtap) n ar5	US-P PUB;	09:53
		(thr ughh le or through-h l r h l or via	EPO; JPO;	
		or opening)) and le tr d and (wire or	DERWENT;	
		wiring)	IBM_TDB	
501	1164	(stack or stacking or stacked) and	USPAT;	2004/06/17
		((substrate or interposer or tape) near5	US-PGPUB;	09:53
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
		or lower or second) near5 (chip or ic))		
502	990	(stack or stacking or stacked) and	USPAT;	2004/06/17
		((substrate or interposer or tape) near5	US-PGPUB;	09:54
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
		or lower or second) near5 (chip or ic)) and		
		(mount or mounted or mounting)		
503	657	(stack or stacking or stacked) and	USPAT;	2004/06/17
		((substrate or interposer or tape) near5	US-PGPUB;	09:54
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM_TDB	
		or lower or second) near5 (chip or ic)) and		
		(mount or mounted or mounting) and adhesive		
504	395	(stack or stacking or stacked) and	USPAT;	2004/06/17
304	333	((substrate or interposer or tape) near5	US-PGPUB;	09:55
		(throughhole or through-hole or hole or via	EPO; JPO;	03.33
		or opening)) and electrode and (wire or	DERWENT;	
		wiring) and ((first or upper or top or bottom	IBM TDB	
		or lower or second) near5 (chip or ic)) and		
		(mount or mounted or mounting) and		
		adhesive and ((insulating or dielectric or		
		nonconductive or non-conductive or		
		nonconducting or non-conducting) near5		
		(substrate or interposer or tape))		
505	84	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and electrode and	DERWENT;	
		(wire or wiring) and ((first or upper or top or	IBM_TDB	
	:	bottom or lower or second) near5 (chip or		
	:	ic)) and (mount or mounted or mounting)		
		and adhesive and ((insulating or dielectric		
		orn n nductiv rnon-conductive r		
		non onducting or non-conducting) near5		
<u> </u>		(ubstrate r interp ser r tape))		

506	41	(sta k r stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate rint rpo r rtap) near5	US-P PUB;	09:56
		(thr ughh I orthrough-h le rh le orvia	EPO; JPO;	
:		r pening)).ti,ab,clm. and el trod and	DERWENT;	
			l .	
		(wire r wiring) and ((first r upper or top or	IBM_TDB	
		bott m r lower or s nd) near5 (chip or		,
		ic)) and (mount or mounted or mounting)		
		and adhesive and ((insulating or dielectric		:
		or nonconductive or non-conductive or		
		nonconducting or non-conducting) near5		
		(substrate or interposer or tape)).ti,ab,clm.		
507	19	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and	DERWENT;	
		electrode.ti,ab,clm. and (wire or wiring) and	IBM_TDB	
		((first or upper or top or bottom or lower or	_	
		second) near5 (chip or ic)) and (mount or		
		mounted or mounting) and adhesive and		
		((insulating or dielectric or nonconductive		
		or non-conductive or nonconducting or		
		non-conducting) near5 (substrate or		
		interposer or tape)).ti,ab,clm.		
508	18	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
300	"		US-PGPUB;	09:56
		and ((substrate or interposer or tape) near5	•	กละอด
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and	DERWENT;	
		electrode.ti,ab,clm. and (wire or	IBM_TDB	
		wiring).ti,ab,clm. and ((first or upper or top		
		or bottom or lower or second) near5 (chip		
		or ic)) and (mount or mounted or mounting)		
		and adhesive and ((insulating or dielectric		
		or nonconductive or non-conductive or		
		nonconducting or non-conducting) near5		
		(substrate or interposer or tape)).ti,ab,clm.		
509	9	(stack or stacking or stacked).ti,ab,clm.	USPAT;	2004/06/17
		and ((substrate or interposer or tape) near5	US-PGPUB;	09:56
		(throughhole or through-hole or hole or via	EPO; JPO;	
		or opening)).ti,ab,clm. and	DERWENT;	
		electrode.ti,ab,clm. and (wire or	IBM_TDB	
		wiring).ti,ab,clm. and ((first or upper or top		
		or bottom or lower or second) near5 (chip		
		or ic)).ti,ab,clm. and (mount or mounted or		
		mounting) and adhesive and ((insulating or		
		dielectric or nonconductive or		
		non-conductive or nonconducting or		
]		non-conducting) near5 (substrate or		,
		int rposer rtap)).ti,ab,clm.		